Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	110mΩ@10V	3A
	160mΩ@4.5V	

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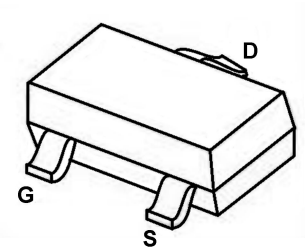
Feature

- High power and current handing capability
- Surface mount package

Application

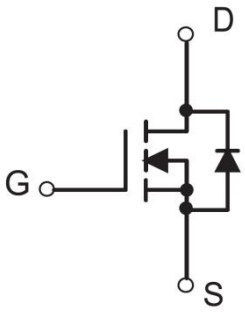
- Battery Switch
- DC/DC Converter

Package

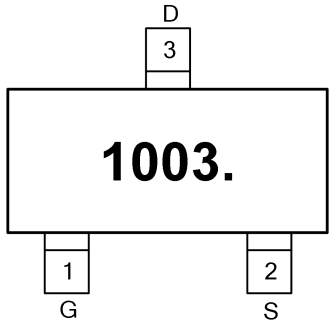


SOT-23-3L

Circuit diagram



Marking



1003. :Device Code

Order Information

Device	Package	Unit/Tape
SP010N110GT1	SOT-23-3L	3000

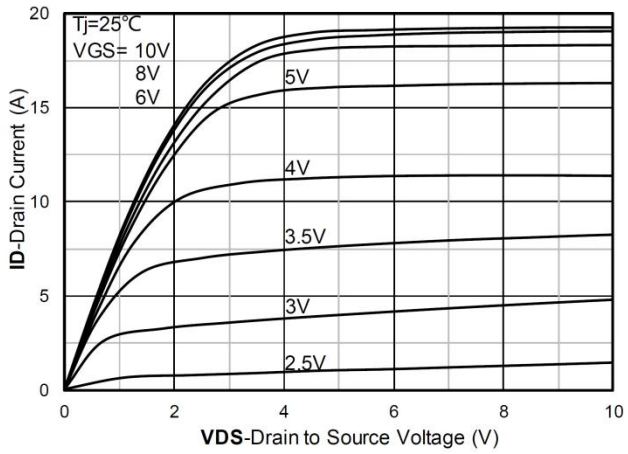
Absolute maximum ratings (Ta=25℃, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	±20	V
Continuous Drain Current (Ta=25℃)	I_D	3	A
Continuous Drain Current (Ta=100℃)	I_D	2	A
Pulse Drain Current Tested	I_{DM}	12	A
Power Dissipation (Ta=25℃)	P_D	1.2	W
Power Dissipation (Ta=100℃)	P_D	0.48	W
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	104	°C/W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

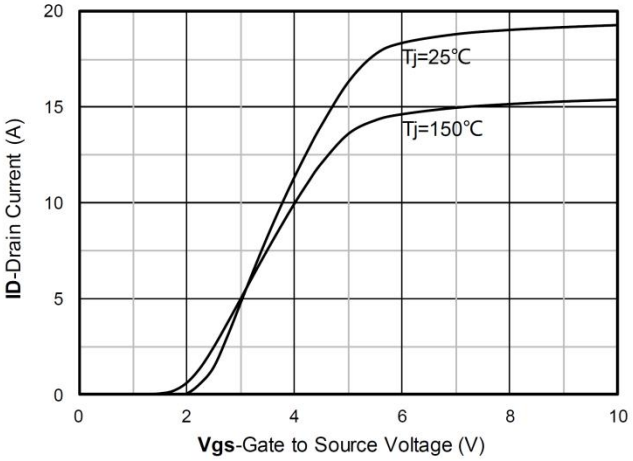
Electrical characteristics (Ta=25℃, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	VGS=0V , ID=250μA	100	-	-	V
Drain-Source Leakage Current	I_{DSS}	VDS=80V , VGS=0V	-	-	1	uA
Gate-Source Leakage Current	I_{GSS}	VGS=±20V , VDS=0V	-	-	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	VDS=VGS , ID=250μA	1.0	1.6	2.2	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	VGS=10V , ID=3A	-	110	140	mΩ
		VGS=4.5V , ID=2A	-	160	210	
Gate Resistance	R_G	VDS=50V , VGS=0V , f=1MHz	-	21	-	Ω
Dynamic characteristics						
Input Capacitance	C_{iss}	VDS=50V , VGS=0V , f=1MHz	-	133	-	pF
Output Capacitance	C_{oss}		-	28	-	
Reverse Transfer Capacitance	C_{rss}		-	2.8	-	
Total Gate Charge	Q_g	VDS=50V , VGS=10V , ID=1.8A	-	2.4	-	nC
Gate-Source Charge	Q_{gs}		-	0.16	-	
Gate-Drain Charge	Q_{gd}		-	0.54	-	
Gate Pleteau Vlotage	$V_{pleteau}$		-	2.6	-	V
Switching Characteristics						
Turn-On Delay Time	$t_{d(on)}$	VDD=50V , VGS=10V , RG=3Ω , ID=1.8A	-	3.6	-	nS
Turn-On Rise Time	t_r		-	14.8	-	
Turn-Off Delay Time	$t_{d(off)}$		-	13.5	-	
Turn-Off Fall Time	t_f		-	20.5	-	
Source-Drain Diode characteristics						
Diode Forward Voltage	V_{SD}	VGS=0V , IS=1A , TJ=25℃	-	-	1.2	V
Maximum Body-Diode Continuous Current	I_S		-	-	3	A
Reverse Recovery Time	Trr	IS=1.8A , di/dt=100A/us , TJ=25℃	-	28.5	-	nS
Reverse Recovery Charge	Qrr		-	45.5	-	nC

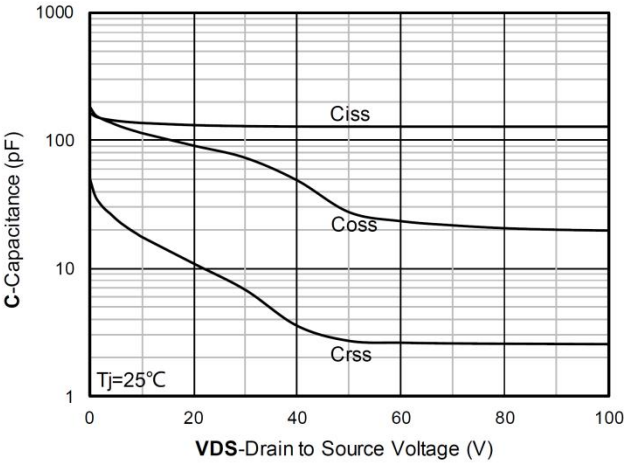
Typical Characteristics



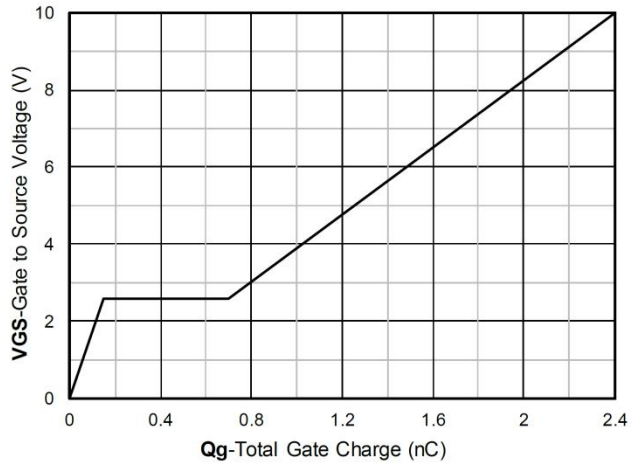
Output Characteristics



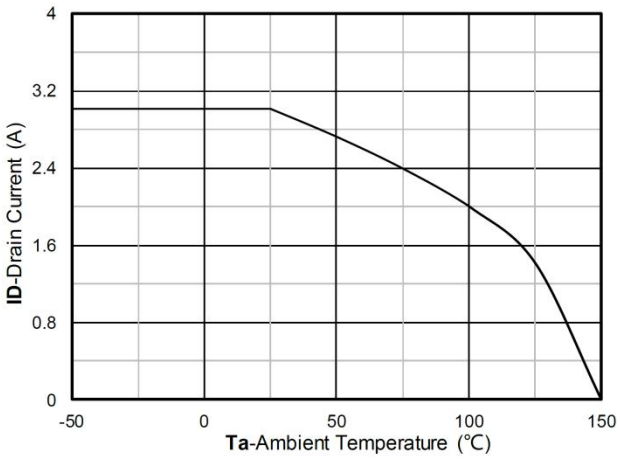
Transfer Characteristics



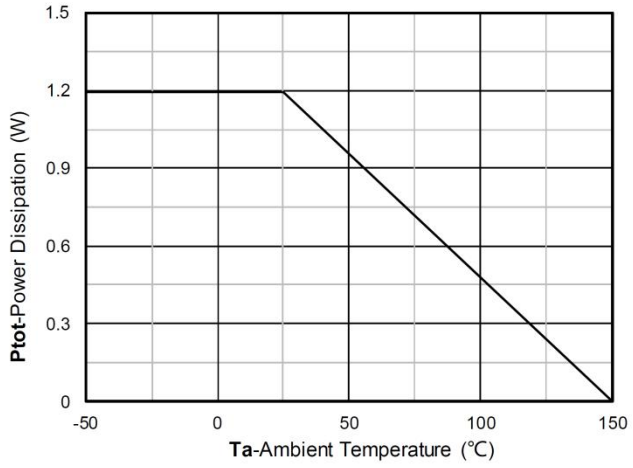
Capacitance Characteristics



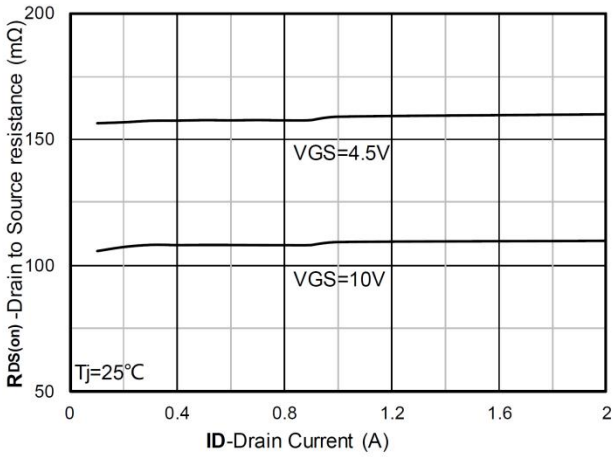
Gate Charge



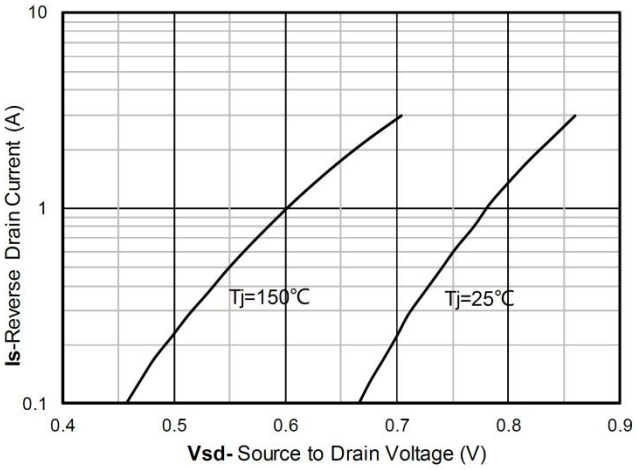
Current dissipation



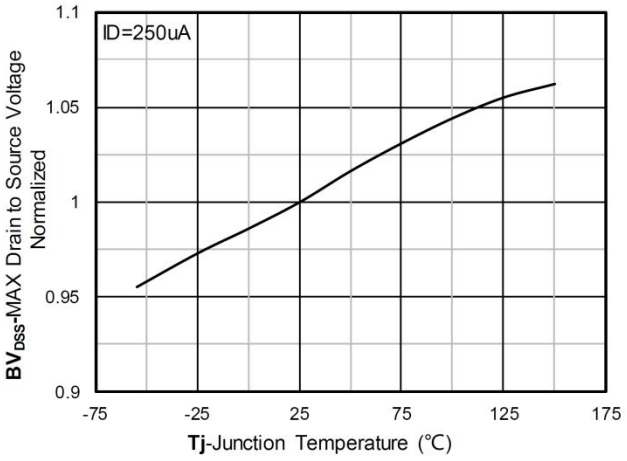
Power dissipation



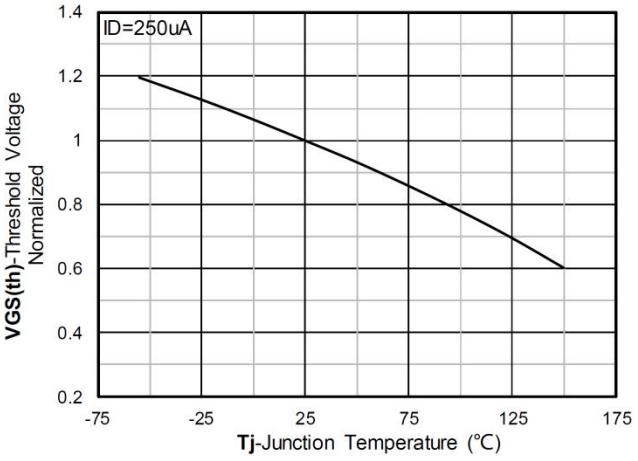
$R_{DS(on)}$ VS Drain Current



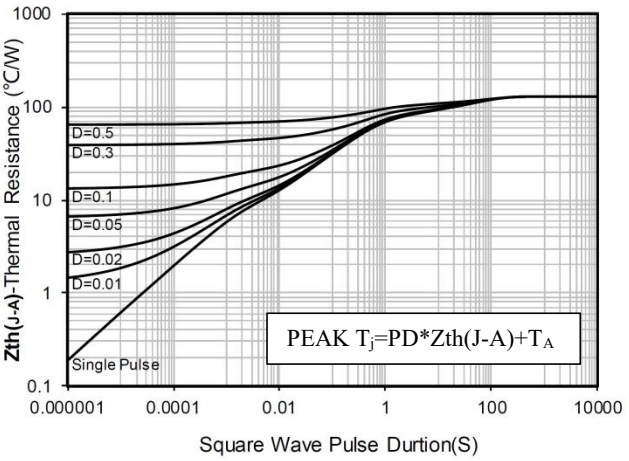
Forward characteristics of reverse diode



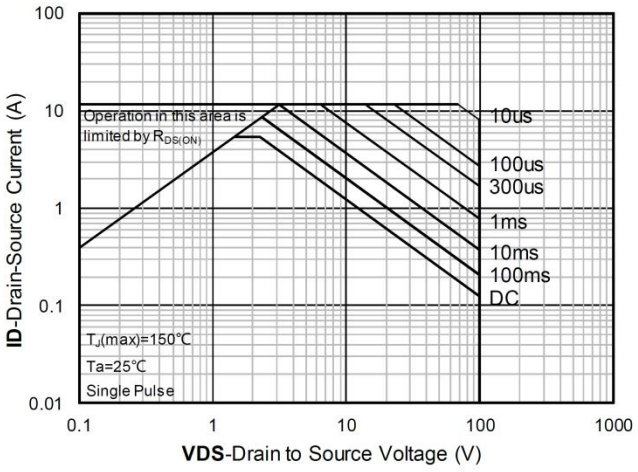
Normalized breakdown voltage



Normalized Threshold voltage



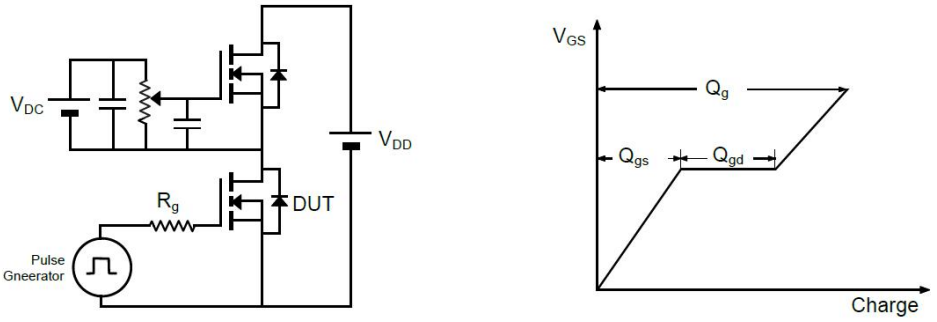
Maximum Transient Thermal Impedance



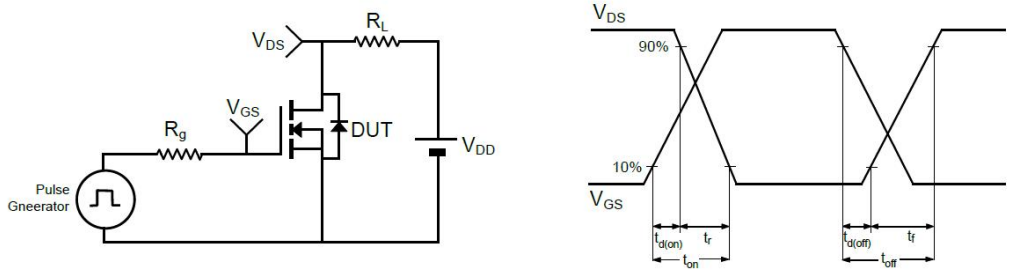
Safe Operation Area

Test Circuit

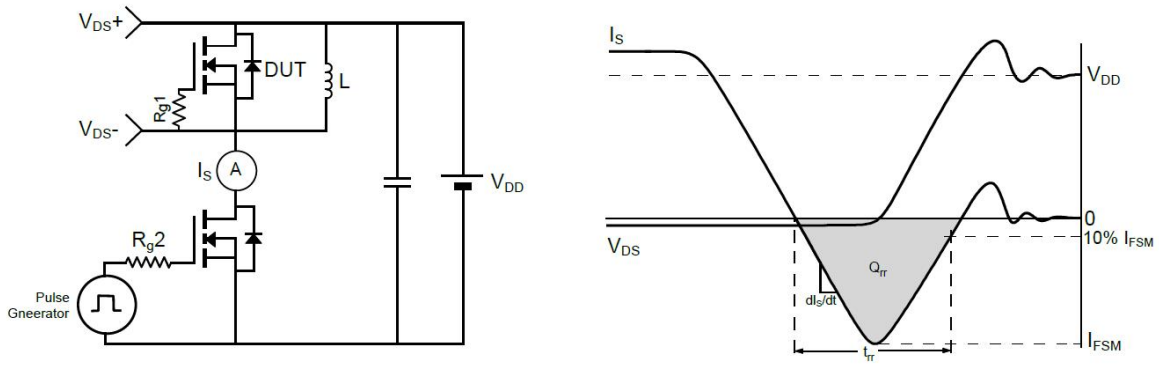
Gate Charge



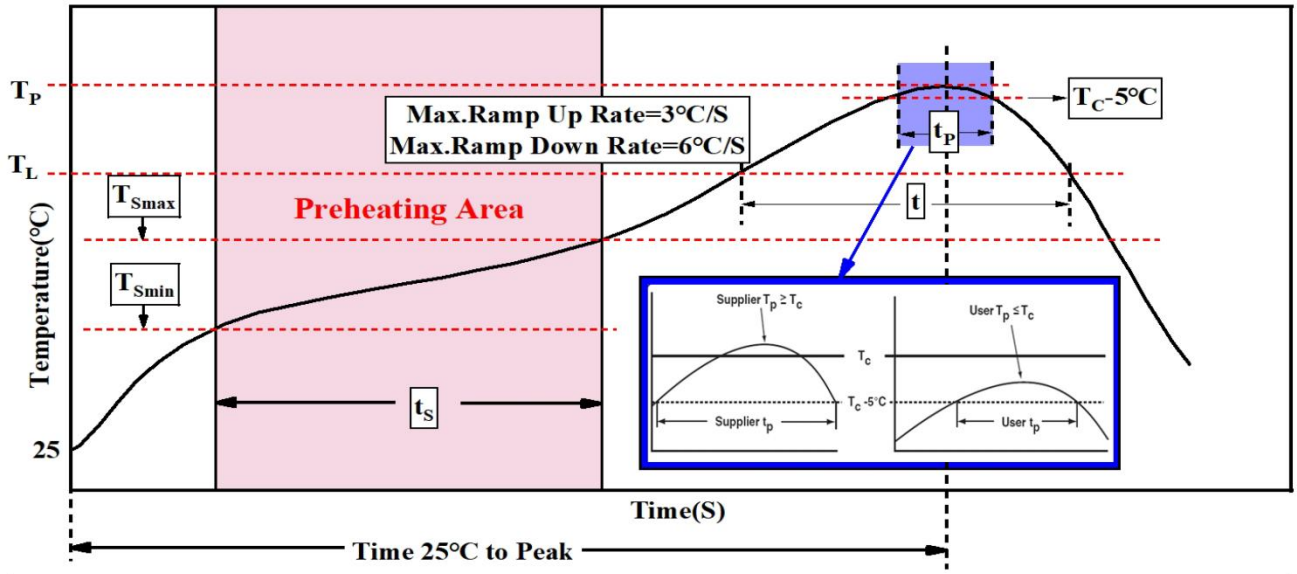
Resistive Load Switching Time



Drain-Source Body Diode Reverse Recovery



Temperature Profile for IR Reflow Soldering



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-120 seconds
Average ramp-up rate (Tsmax to Tp)	3 °C/second max.	3°C/second max.
Liquidous temperature (TL) Time at liquidous (tL)	183 °C 60-150 seconds	217°C 60-150 seconds
Peak package body Temperature e (Tp)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (tp)** within 5°C of the specified classification temperature (Tc)	20** seconds	30** seconds
Average ramp-down rate (Tp to Tsmax)	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (Tp) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum		

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

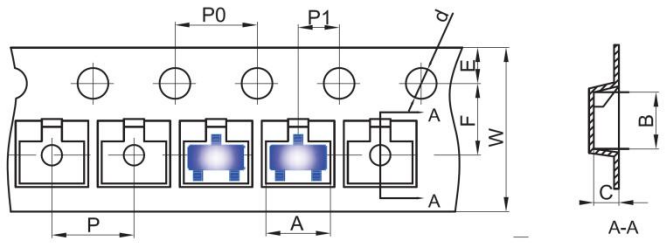
Package Thickness	Volume mm^3 <350	Volume mm^3 ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

SOT-23-3L Tape and Reel

SOT-23-3L Embossed Carrier Tape

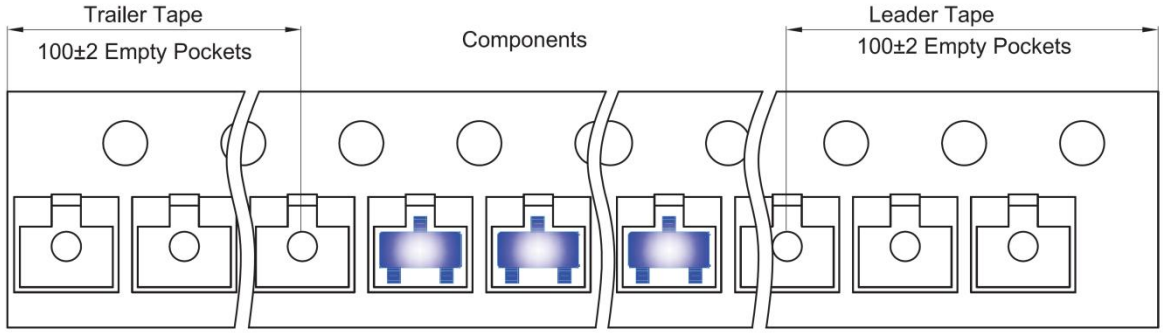


Packaging Description:

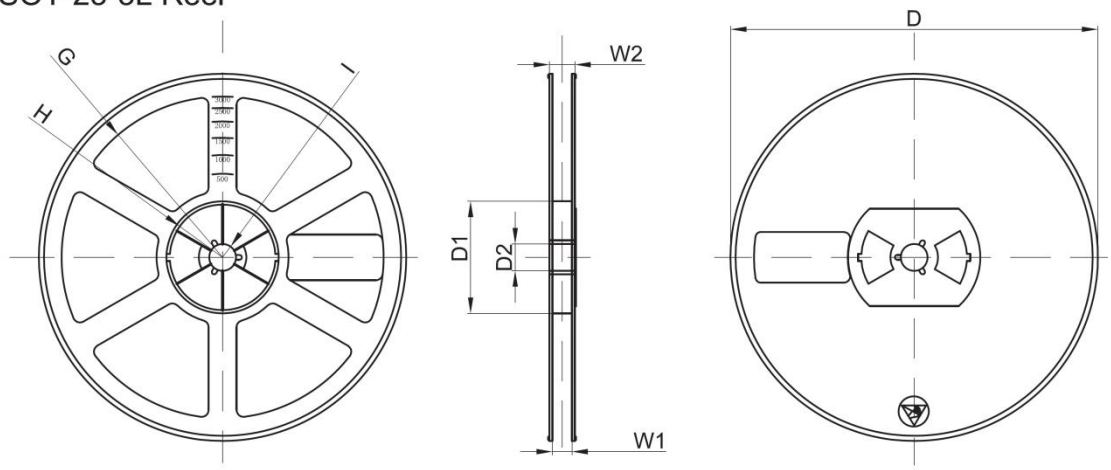
SOT-23-3L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 18.0cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

Dimensions are in millimeter										
Pkg type	A	B	C	d	E	F	P0	P	P1	W
SOT-23-3L	3.18	3.28	1.32	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23-3L Tape Leader and Trailer



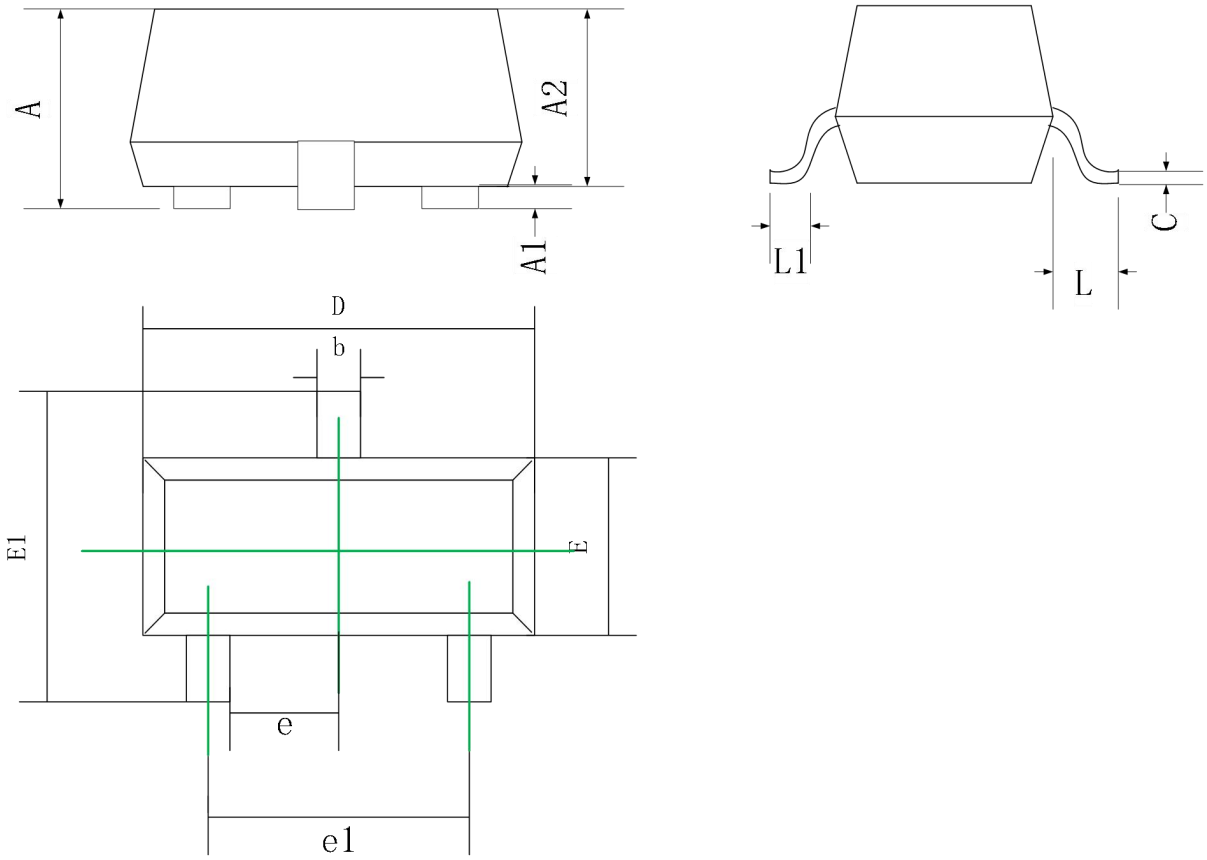
SOT-23-3L Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
7"Dia	Ø180.00	60.00	13.00	R78.00	R25.60	R6.50	9.50	13.10

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	

SOT-23-3L Package Information



Symbol	Dimensions in millimeters	
	Min.	Max.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.300	0.500
c	0.100	0.200
D	2.820	3.020
E	1.500	1.700
E1	2.650	2.950
e	0.950 Typ.	
e1	1.800	2.000
L	0.300	0.600
θ	0°	8°